

IN THE CLAIMS:

Please cancel Claim 1, without prejudice or disclaimer of subject matter.

Please add new Claims 16-25 to read as follows.

The following is a complete listing of the claims in this application, reflects all changes made to the claims, and replaces all earlier versions and all earlier listings of the claims:

1. (Cancelled)

--16. (New) A method of manufacturing an electron source comprising steps of:

exposing, of a surface of a substrate to a sealed atmosphere, on which a plurality of electron-emitting devices are to be formed; and
introducing, of a gas containing carbon into the sealed atmosphere, wherein the sealed atmosphere is formed by a chamber and the chamber is heated before said introducing step.

17. (New) A method of manufacturing an electron source comprising steps of:

exposing, of a surface of a substrate to a sealed atmosphere, on which a plurality of electron-emitting devices are to be formed; and
introducing, of a gas containing carbon into the sealed

atmosphere,

wherein the sealed atmosphere is formed by a chamber and the chamber is heated before said introducing step, to reduce a moisture absorbed to a surface of the chamber.

18. (New) A method of manufacturing an electron source comprising steps of:

exposing, of a surface of a substrate to a sealed atmosphere,

wherein an electron-emitting region to be formed is disposed on the surface of the substrate; and

introducing, of a gas containing carbon into the sealed atmosphere,

wherein the sealed atmosphere is formed by a chamber and the chamber is heated before said introducing step.

19. (New) The method according to Claim 18, further comprising a step of applying a voltage to an electro-conductive member, the electro-conductive member being disposed on the surface of the substrate.

20. (New) A method of manufacturing an electron source comprising steps of:

exposing, of a surface of a substrate to a sealed atmosphere,

wherein an electro-conductive member, in which an electron-emitting region is to be formed, is disposed on the surface of the substrate; and
introducing, of a gas containing carbon into the sealed atmosphere,
wherein the sealed atmosphere is formed by a chamber and the chamber is heated before said introducing step, to reduce a moisture absorbed to a surface of the chamber.

21. (New) The method according to Claim 20, further comprising a step of applying a voltage to the electro-conductive member.

22. (New) A method of manufacturing an electron source comprising steps of:
exposing, of a surface of a substrate to a sealed atmosphere,
wherein an electro-conductive member, capable of being subjected to an activation of an electron-emitting function, is disposed on the surface of the substrate;
and
introducing, of a gas containing carbon into the sealed atmosphere,
wherein the sealed atmosphere is formed by a chamber and the chamber is heated before said introducing step.

23. (New) The method according to Claim 22, further comprising a step of applying a voltage to the electro-conductive member.

24. (New) A method of manufacturing an electron source comprising steps of:

exposing, of a surface of a substrate to a sealed atmosphere,

wherein an electro-conductive member, capable of being subjected to an activation of an electron-emitting function, is disposed on the surface of the substrate; and

introducing, of a gas containing carbon into the sealed atmosphere,

wherein the sealed atmosphere is formed by a chamber and the chamber is heated before said introducing step, to reduce a moisture absorbed to a surface of the chamber.

25. (New) The method according to Claim 24, further comprising a step of applying a voltage to the electro-conductive member.--